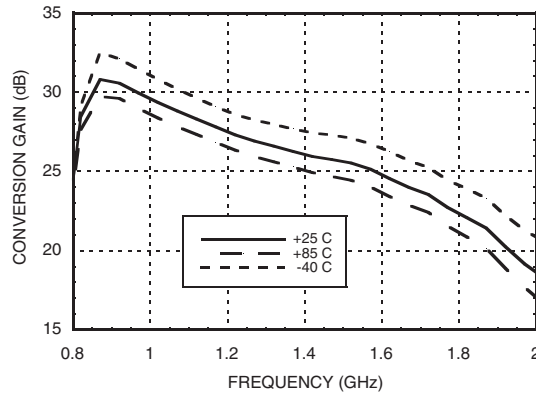
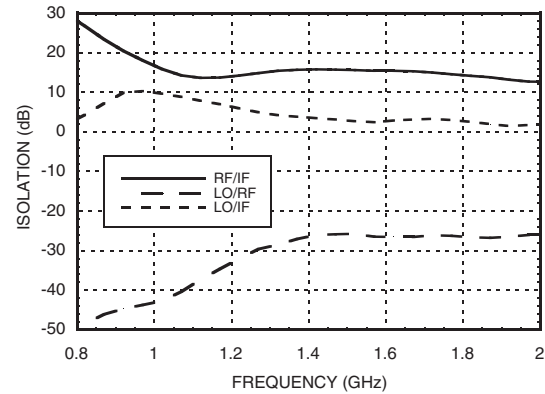


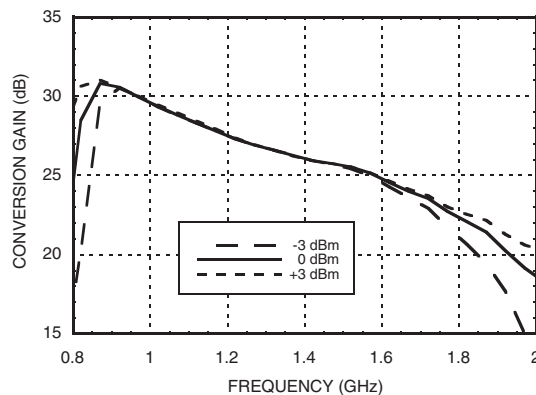
Conversion Gain vs. Temperature



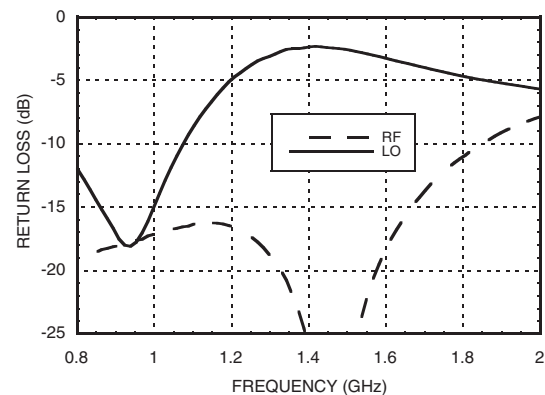
Isolation



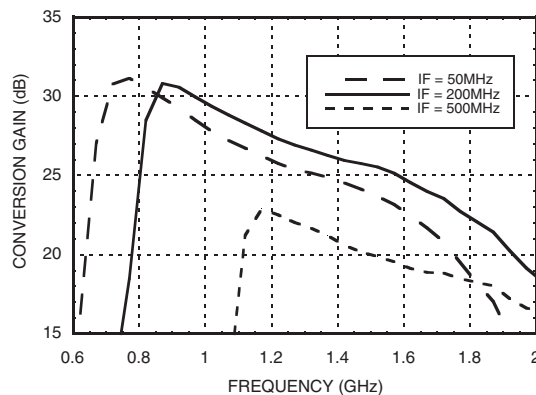
Conversion Gain vs. LO Drive



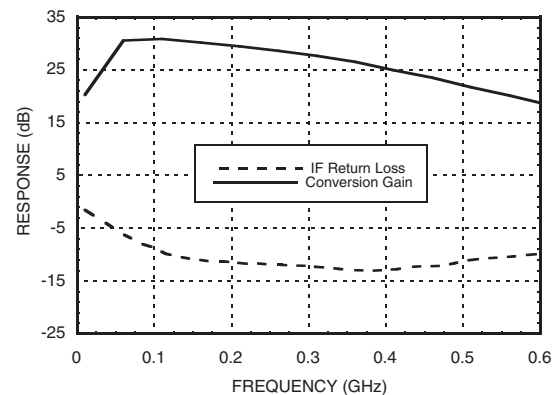
Return Loss



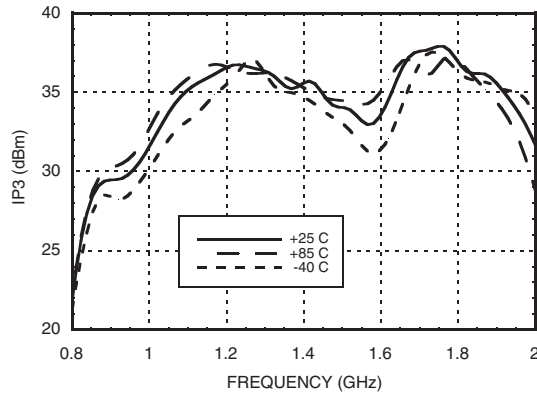
Conversion Gain vs. IF Frequency



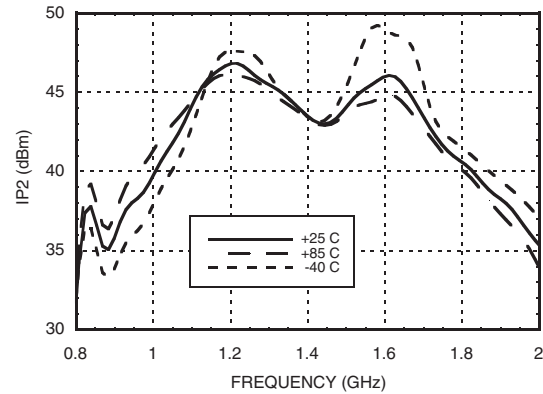
IF Bandwidth, LO = 0.8 GHz



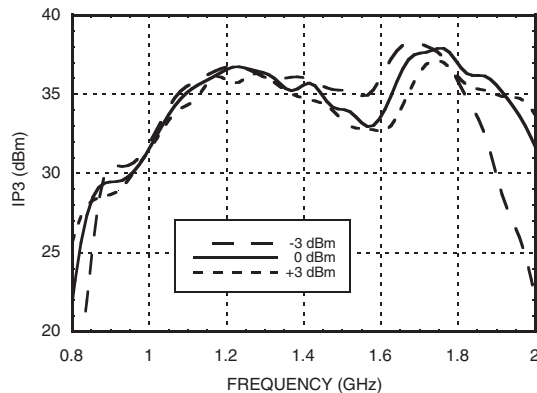
Output IP3 vs. Temperature



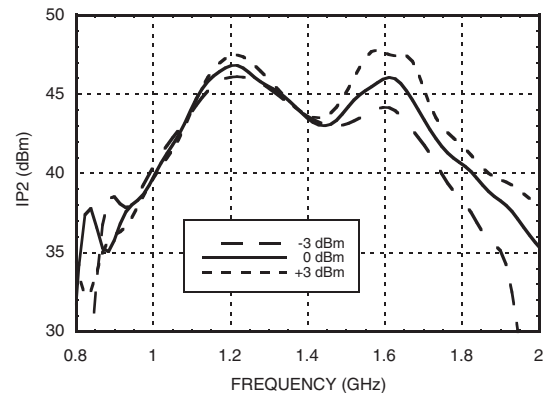
Output IP2 vs. Temperature



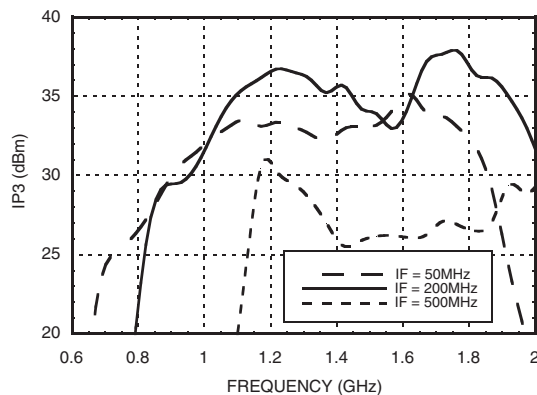
Output IP3 vs. LO Drive



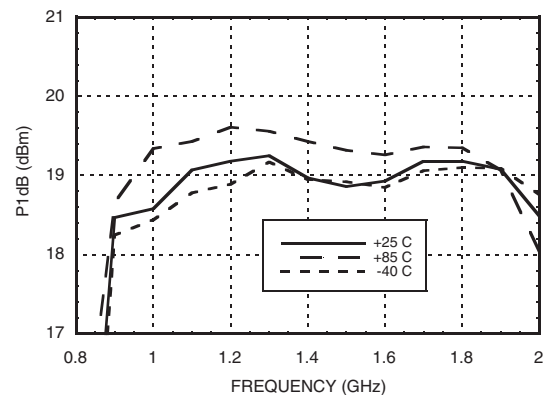
Output IP2 vs. LO Drive



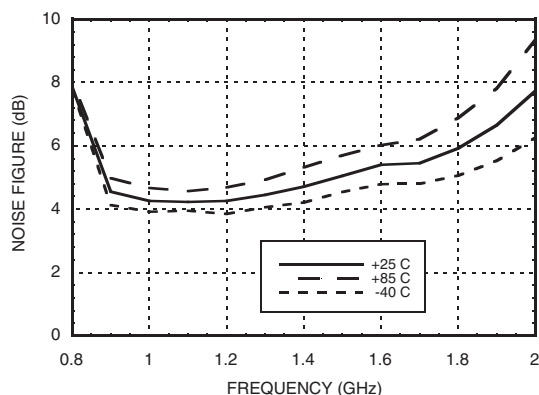
Output IP3 vs. IF Frequency



Output P1dB vs. Temperature



Noise Figure vs. Temperature



Absolute Maximum Ratings

RF / IF Input (Vbias = +5V)	+10 dBm
LO Drive (Vbias = +5V)	+10 dBm
Vbias	+5.5 Vdc
Junction Temperature	150 °C
Continuous P _{diss} (T = 85°C) (derate 20.8 mW/°C above 85°C)	1.36 W
Thermal Resistance (junction to ground paddle)	47.9 °C/W
Storage Temperature	-65 to +150°C
Operating Temperature	-40 to +85°C

Typical Supply Current

Vbias (V)	Ibias (mA)
4.5	210
5.0	250
5.5	290



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Absolute Bias Resistor (R1)

Range & Recommended Bias Resistor Values for I_{dd} RF ^[3]

Vbias (V)	Rbias (R1)			I _{dd} RF
	Min (Ohms)	Max (Ohms)	R1 Ohms	
5V	0	Open Circuit	820	65
			2k	78
			3.92k	88
			10k	90

[3] External bias resistor R1 sets the DC current of the RF Amp

Typical Performance Cascade Analysis

(RF = 900 to 1000 MHz, IF = 50 to 250 MHz, LO = Low Side or High Side)

Description	Component Level					Cumulative MCM Performance				
	Gain (dB)	NF (dB)	OP1dB (dBm)	OIP3 (dBm)	+5V Current	Gain (dB)	OP1dB (dBm)	NF (dB)	OIP3 (dBm)	IIP3 (dBm)
RF LNA	16.0	0.5	21.0	33.5	88.0	16.0	21.0	0.5	33.5	17.5
RF Filter*	-1.5	1.5				14.5	19.5	0.5	32.0	17.5
Passive Mixer w/ LO Amp	-8.5	8.5	14.5	24.5	50.0	6.0	9.4	1.3	21.0	15.0
IF Amp	22.0	2.8	19.5	37.0	88.0	28.0	19.2	2.0	36.0	8.0
HMC621LP4	Cumulative MCM Performance				250.0	28.0	19.2	2.0	36.0	8.0

* RF image rejection filter is not included in the released eval boards.

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1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
4. PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
5. PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
6. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
7. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
8. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

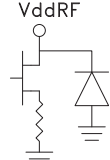
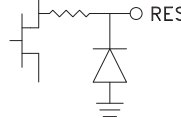
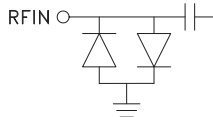
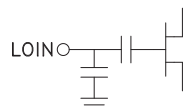
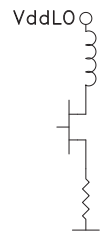
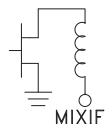
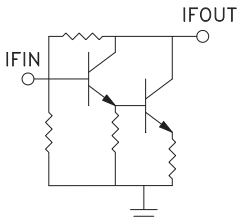
Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC621LP4	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	H621 XXXX
HMC621LP4E	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	<u>H621</u> XXXX

[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	VddRF	Power Supply Voltage for the RF amplifier. Choke inductor and bypass capacitors are required. See application circuit.	
2	RES	This pin is used to set the DC current of the RF amplifier by selection of external bias resistor. See application circuit and bias resistor value table.	
3	RFIN	This pin is matched to 50 Ohms.	
4, 6 - 8, 10, 11, 13, 16, 18 - 20, 23, 24	N/C	No connection necessary. These pins may be connected to RF/DC Ground	
5	GND	Backside of package has exposed metal ground paddle that must also be connected to ground.	
9	LOIN	This pin is AC coupled and matched to 50 Ohms.	
12	VddLO	Power supply for LO amplifier. An external RF bypass capacitor is required.	
14	MIXIF	This pin is DC coupled. For applications not requiring operation to DC this port should be DC blocked externally using a series capacitor. Choose value of capacitor to pass IF frequency desired. For operation to DC, this pin must not sink/source more than 40 mA of current or failure may result.	
15	IFIN	This pin is DC coupled. An off chip DC blocking capacitor is required.	
17	IFOUT	IF output and DC Bias (Vcc) for the output stage.	



MICROWAVE CORPORATION

v01.0708



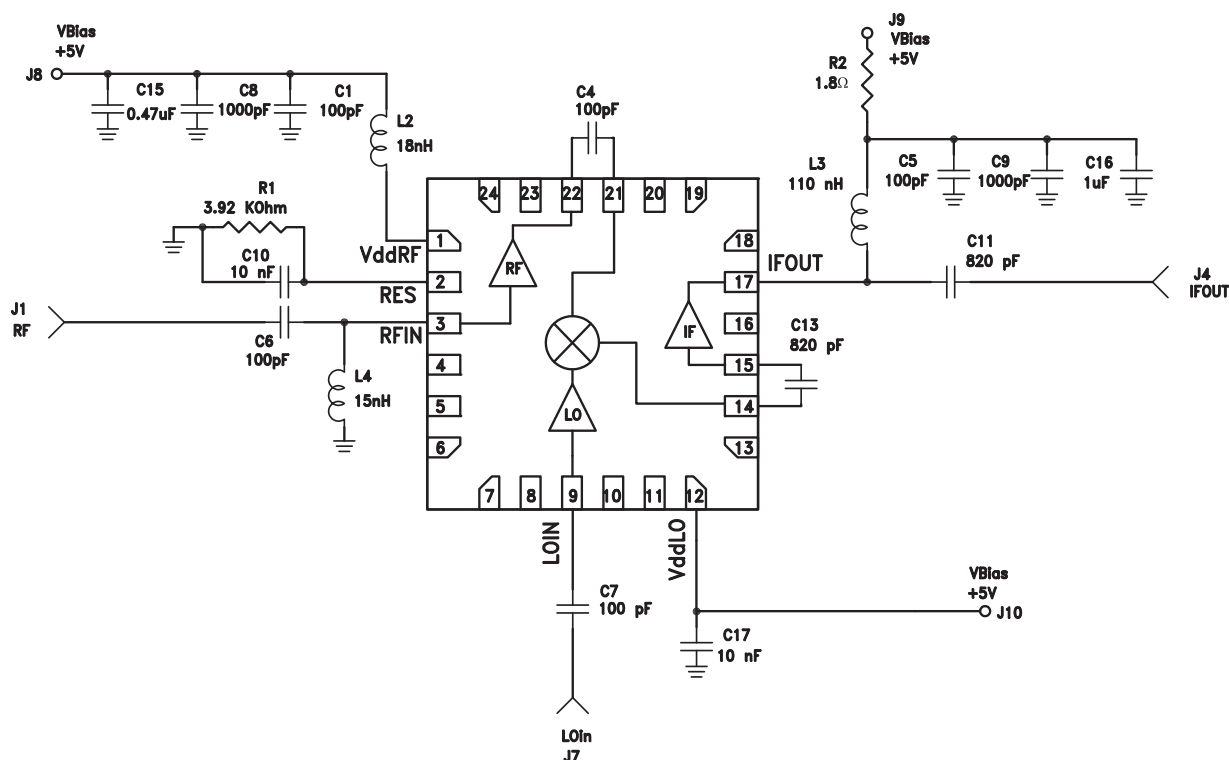
HMC621LP4 / 621LP4E

RFIC DOWNCONVERTER SMT, 0.9 - 1.6 GHz

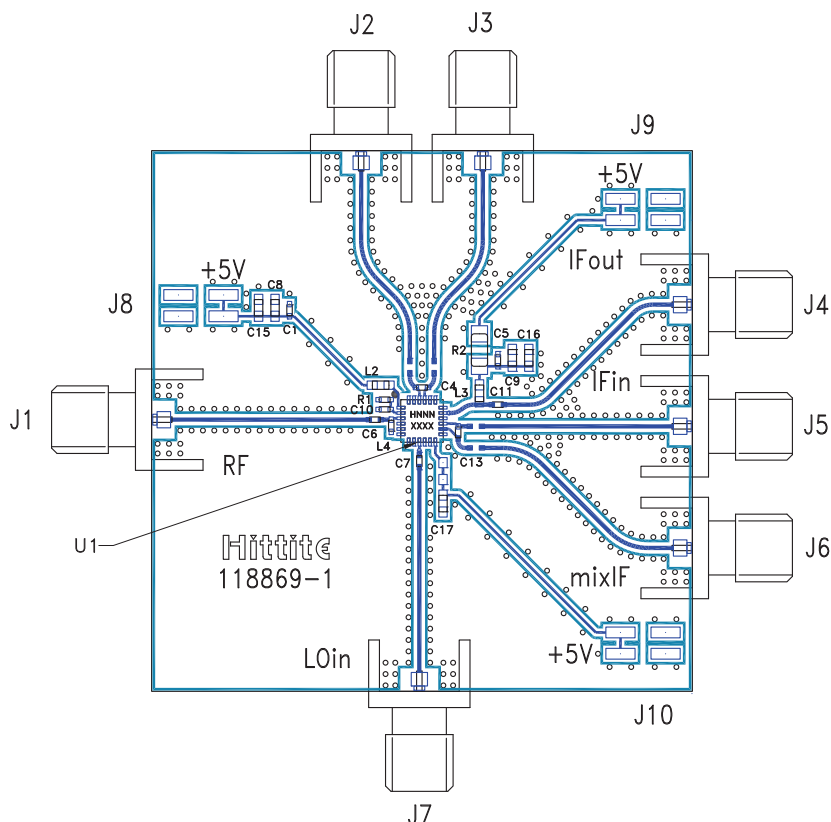
Pin Descriptions (Continued)

Pin Number	Function	Description	Interface Schematic
21	MIXRF	This pin is DC coupled and matched to 50 Ohms.	
22	RFOUT	This pin is matched to 50 Ohms.	

Application Circuit



Evaluation PCB



List of Materials for Evaluation PCB 118841 [1]

Item	Description
J1 - J7	SMA Connector
J8 - J10	2mm 12 pos Vertical Molex Connector
C1, C4 - C7	100 pF Capacitor, 0402 Pkg.
C8, C9	1000 pF Capacitor, 0603 Pkg.
C10	10 nF Capacitor, 0402 Pkg.
C11, C13	820 pF Capacitor, 0402 Pkg.
C15	0.47 μ F Capacitor, 0603 Pkg.
C16	1 μ F Capacitor, 0603 Pkg.
C17	10 nF Capacitor, 0603 Pkg.
R1	3.92k Ohm Resistor, 0402 Pkg.
R2	1.8 Ohm Resistor, 1206 Pkg.
L2	18 nH Inductor, 0603 Pkg.
L3	110 nH Inductor, 0603 Pkg.
L4	15 nH Inductor, 0603 Pkg.
U1	HMC621LP4(E) - Downconverter
PCB [2]	118869 Evaluation Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350 or Arlon 25RF, FR4

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.